



Where **Analog** and **Value** Meet

Corporate Presentation

Q2 2021



Our Global Operations



All of Tower's facilities are:

- ISO14001 Certified
- OHSAS18001 Certified
- Compliant to ISO45001
- ISO9001 Certified
- IATF16949 Certified
- Our US facilities and Uozu, Japan are ITAR compliant.

Migdal Haemek, ISRAEL	Migdal Haemek, ISRAEL	Newport Beach, CA, USA	San Antonio, TX, USA
<ul style="list-style-type: none">• 6" (150mm)• CMOS, CIS, Power, Power Discrete• 1µm to 0.35µm• Planarized BEOL, W and Oxide CMP	<ul style="list-style-type: none">• 8" (200mm)• CMOS, CIS, Power, Power Discrete, RF Analog, MEMS• 0.18µm to 0.13µm• Cu and Al BEOL, EPI, 193nm Scanner	<ul style="list-style-type: none">• 8" (200mm)• CMOS, CIS, RF Analog, MEMS• 0.18µm to 0.13µm• Al BEOL, SiGe, EPI	<ul style="list-style-type: none">• 8" (200mm)• Power, RF Analog• 0.18µm• Al BEOL

Agrate, ITALY	Arai, JAPAN	Tonami, JAPAN	Uozu, JAPAN
<ul style="list-style-type: none">• 12" (300mm)• Analog RF, Power, Displays• 65nm	<ul style="list-style-type: none">• 8" (200mm)• Analog, CIS• 0.13µm to 0.11µm	<ul style="list-style-type: none">• 8" (200mm)• Analog, Power Discrete, NVM, CCD• 0.35µm to 0.15µm	<ul style="list-style-type: none">• 12" (300mm)• Analog, CMOS, CIS, RFCMOS/ SOI• 65nm and 45nm

Semi Market Trends

Wireless Everything

Seamless Connectivity



36%

of corporate revenue

Mobile – up 22% 2020/19

Infrastructure – up 15% 2020/19

Green Everything

Energy Efficiency



32%

of corporate revenue

PMIC – up 25% organic 2020/19

Discrete – down 12% 2020/19

Smart Everything

Interactive Smart Systems



18%

of corporate revenue

Up 7% 2020/19

High Quality and Flexibility of Worldwide Manufacturing Capabilities

Migdal Haemek, Israel



6", 150mm
Sensors, Power
1 μ m to 0.35 μ m

Migdal Haemek, Israel



8", 200mm
Sensors, Power, RF SOI
0.18 μ m to 0.13 μ m

Newport Beach, USA



8", 200mm
SiGe, MEMS, RF SOI
0.5 μ m to 0.13 μ m

San Antonio, USA



8", 200mm
RF SOI, Power
0.18 μ m

Tonami, Japan



8", 200mm
Power
0.18 μ m

Arai, Japan



8", 200mm
Sensors, RF SOI
0.13 μ m to 0.11 μ m

Uozu, Japan



12", 300mm
Power, Sensors, RF SOI
65nm & 45nm

Agrate, Italy



12", 300mm
Analog RF, Power, Displays
65nm

Enabling 200mm multi-fab wafer production

- Cross qualified platforms enabling maximized utilization and customer assurance
- Cross qualification answer customers BCP needs

Analog Technologies for Connected Automated Vehicles

Served by Tower Semiconductor

Application

ADAS: Radar, V2X
Automotive Ethernet



ADAS: LiDAR, Camera
& Night Vision IR



Diagnostic, Dynamics,
Comfort & Convenience



EV Battery Management
& Powertrain



Technology

RF & HPA

- RF-SOI
- RF CMOS
- SiGe BiCMOS
- III-V
- MEMS
- Silicon Photonics

Light Sensing

- CMOS image sensors
- CCDs
- PIN
- ToF: SPADs (LiDAR)
- SWIR image sensors
- Thermal (IR) imaging



Multi-Stimuli Sensing

- Magnetic TMR
- Biometric
- Inertial
- Temperature, Pressure
- Gas/Fluid
- Load, Torque, Speed

HV Power

- BCD (bulk, SOI)
- NVM
- MOSFETs
- IGBT
- GaN
- SiC

RF Major Markets and Technology Solutions

Markets	Products Enabled	Technology	
 Mobile (5G Handsets)	RF Switch; LNA; Antenna Tuner	RF SOI	200 and 300mm; 70fs Ron-Coff
	WiFi/BT PA; LNA	RF SiGe	Best-in-class noise and PAE
 Optical Transceivers (Datacenter/Telecom)	100-800Gb/s TIA; LD; CDR	HP SiGe	>300GHz Ft; >60% market share
	Integrated Optical Components	SiPho	Production Foundry Technology C and O band components >70GHz Photo Detector, >30GHz Modulator Low loss waveguides and couplers

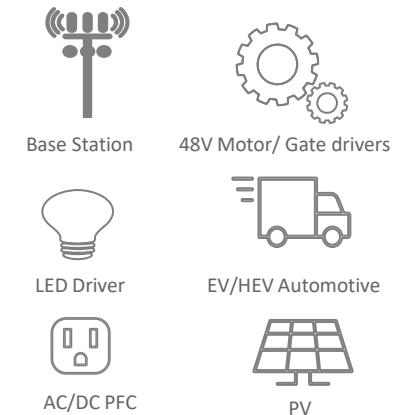
Power Technology Fit & Roadmap



Available	
12" Japan 65nm Design Rules 5V-only & 1.2V/5V Top Cu 3.3um & 2x3.3um 5V Lib: 113kgates/mm ² 1.2V Lib: 850kgates/mm ² OTP, FTP	5V ~ 16V LDMOS 5V: 0.9mΩmm ² @ 11.5V BV 16V: 4.5mΩmm ² @ 26.5V BV

In Development
1.2V-Only Analog& LDMOS
20V, 24V (34V BV) LDMOS
32~256Kb MTP
Backend eNVM Full flash

World's Best BCD up to 24V operation



8" Israel & Japan 5V-only & 1.8V/5V Top Al & Cu 5V Lib: 90kgates/mm ² 1.8V Lib: 115kgates/mm ² OTP, FTP, MTP	5V~ 30V Gen4 10mΩmm ² @ 32V BV	5V~ 24V Gen6 6.3mΩmm ² @ 34V BV
	30V~ 140V RESURF (HS/ISO) 22mΩmm ² @ 50V BV 180mΩmm ² @ 140V BV	
	160V SOI 200V BV	

kV Galvanic Capacitor
SiCr TFR Resistor
Deep Trench Isolation
200V RESURF (nonSOI)
220V SOI 300V BV


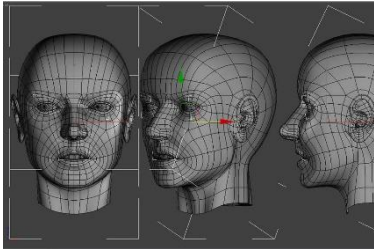
Widest offering with extensive capabilities

Image Sensors Growing Markets

• Tower Traditional Markets

Medical and Dental X-Ray 	<ul style="list-style-type: none">• Intra and Extra Oral• Mammography• Surgical• Up to 21cm x 21cm in one die
High end Photography 	<ul style="list-style-type: none">• Cinematography• Broadcasting• High end DSLR• Mirror-less
Industrial Machine Vision 	<ul style="list-style-type: none">• 2-D barcode readers• Food inspection• Industrial robots• Screen Inspection QA• ITS

• New Emerging High Growth Markets

Under Screen Fingerprint 	<ul style="list-style-type: none">• Under OLED lens-type and 1:1 sensors• Under LCD lens-type sensors
Time of Flight – 3D 	<ul style="list-style-type: none">• Face recognition• Lidars• AR based commerce• Education• Gaming• iToF and dToF

Non Imaging Sensors applications

Remote Temperature sensors

- High sensitivity and accuracy
- Broad Temperature range



- ✓ Mobile /IoT
- ✓ Industrial
- ✓ Automotive
- ✓ Medical
- ✓ Security

Time-temperature Indicators

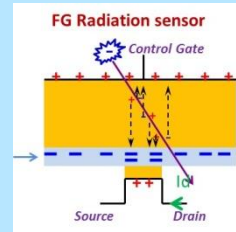
- No power supply
- CMOS embedded
- Reusable



- ✓ Food Industry
- ✓ Agriculture
- ✓ Medical

Floating Gate radiation sensors

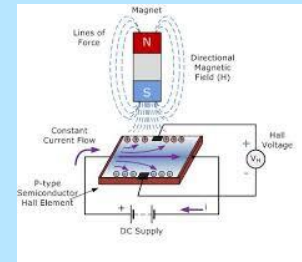
- No power supply
- Direct: no scintillator
- Reusable



- ✓ Radiation monitors
- ✓ Badges
- ✓ Sterilization
- ✓ Radon detectors

Magnetic sensors

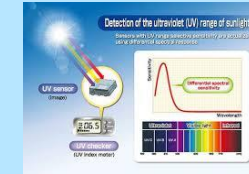
- High temperature GaN based
- High sensitivity TMR



- ✓ Industrial
- ✓ Automotive
- ✓ Consumer
- ✓ Space

UV sensing

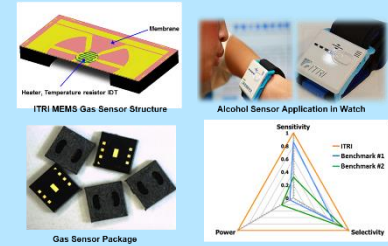
- Solar blind
- Record sensitivity
- Operation at HT



- ✓ Skin protection
- ✓ Flame diagnostics
- ✓ Free space optical communication
- ✓ Sterilization
- ✓ Industrial automation

Gas and Humidity

- Operation at HT
- Easy reset
- Sensor fusion



- ✓ Automotive
- ✓ Environmental
- ✓ Industrial
- ✓ Medical



Displays



Tower Semiconductor History

1993



Tower Semiconductor was founded with the acquisition of National Semiconductor's 150-mm wafer fabrication facility.

1994



Tower Semiconductor became a public company. Shares began to be traded on NASDAQ (TSEM).

2000



Design it once design it right: The Worldwide Design Center was established in Netanya, Israel.

2001



Tower Semiconductor shares began to be traded on Tel Aviv Stock Exchange (TSEM).

2004



Established an adjacent, state-of-the-art facility (Fab 2) in Migdal Haemek Israel, designed to operate in geometries of 0.18-micron and below, using advanced CMOS technology.

2008



Tower Semiconductor and Jazz Semiconductor merged in a stock for stock transaction and the combined companies officially launched as TowerJazz.

2014



Completed a joint venture with Panasonic Corporation. The joint venture added available capacity of approximately 800,000 wafers per year (8" equivalent) in three manufacturing facilities in Japan; one 300mm and two 200mm.

2016



Acquired Maxim Integrated's 8-inch wafer fabrication facility in San Antonio, TX, USA.

2020



On March 1st, 2020, launched a new brand identity to reflect company's global presence and strength, and highlight its focus to provide the highest value analog semiconductor solutions.

2021



Announced partnership with ST Microelectronics to accelerate Agrate, Italy 300mm analog and power fab capacity and utilization ramp-up.



Tower Semiconductor Quality Policy and Certifications

Committed to high Quality and Customer Satisfaction

- ✓ Meet or exceed customer expectations
- ✓ Provide outstanding manufacturing services with high yields and on-time delivery
- ✓ Continuously improve efficiency and effectiveness of processes, procedures, and systems through fast cycles of learning
- ✓ Meet applicable regulatory & statutory requirements



A Resilient Growth Company in a Challenging Environment

- **Well experienced, matured and strong global company** – with solid and enviable balance sheet and net cash financial position, exceptional analog technology solutions and manufacturing capabilities, high level expertise and talents.

Excellence in leadership, partnership, impact & innovation

- **Long-term partnerships** – based upon unparalleled trust, mutual roadmap creation and shared success.
- **Leading the analog ecosystem in exciting growth markets, providing strong competitive advantage with full circle value creation.**



Where **Analog** and **Value** Meet

Thank You

www.towersemi.com

